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 Inputs Are TTL-Voltage Compatible Flow-Through Architecture Optimizes PCB 	DB, DW, N, OR PW PACKAGE (TOP VIEW)					
Layout	1Y 1 20 1A					
 Center-Pin V_{CC} and GND Configurations	2Y [2 19] 2A					
Minimize High-Speed Switching Noise	3Y [3 18] 3A					
 EPIC[™] (Enhanced-Performance Implanted	GND [4 17] NC					
CMOS) 1-µm Process	GND [5 16] V _{CC}					
 500-mA Typical Latch-Up Immunity at	GND [6 15] V _{CC}					
125°C	GND [7 14] NC					
 Package Options Include Plastic	4Y [8 13] 4A					
Small-Outline (DW), Shrink Small-Outline	5Y [9 12] 5A					
(DB), and Thin Shrink Small-Outline (PW)	6Y [10 11] 6A					
Packages and Standard Plastic (N) 300-mil						

NC – No internal connection

description

DIPs

This device contains six independent inverters. It performs the Boolean function $Y = \overline{A}$.

The 74ACT11004 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each inverter) INPUT OUTPUT Y A H L Н logic symbol[†] 20 1 1 1Y 1A 19 2 2A 2Y 18 3 3A 3Y 8 13 **4A 4**Y 12 9 5A 5Y 11 10 6A 6Y

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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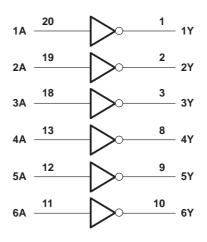
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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		0.8	V
VI	Input voltage	0	VCC	V
Vo	Output voltage	0	VCC	V
IOH	High-level output current		-24	mA
IOL	Low-level output current		24	mA
$\Delta t / \Delta v$	Input transition rise or fall rate	0	10	ns/V
Т _А	Operating free-air temperature	-40	85	°C



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	ER TEST CONDITIONS	Vee	T _A = 25°C		MIN	MAY	UNIT	
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	IVIIIN	MAX	UNIT
		4.5 V	4.4			4.4		
	I _{OH} = -50 μA		5.4			5.4		V
VOH	I _{OH} = -24 mA		3.94			3.8		
			4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
	I _{OL} = 50 μA				0.1		0.1	
					0.1		0.1	
VOL	la. 24 mA	4.5 V			0.36		0.44	V
	I _{OL} = 24 mA				0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
lj	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μA
ICC	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			4		40	μA
ΔI_{CC}	One input at 3.4 V, \qquad Other inputs at GND or V _{CC}	5.5 V	- 15		0.9		1	mA
Ci	$V_I = V_{CC} \text{ or } GND$	5 V		3.5				pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ns.

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended ranges of supply voltage and free-air temperature (unless otherwise noted) (see Figure 1)

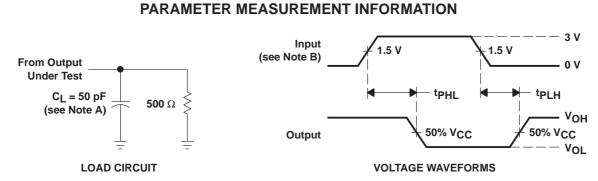
PARAMETER	FROM	то		T _A = 25°C			MAX	UNIT
FARAWETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	IVIAA	UNIT
^t PLH		V	1.5	5.3	9	1.5	9.7	
^t PHL	A		1.5	6.4	8.7	1.5	9.6	ns

operating characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

PARAMETER		TEST CO	TYP	UNIT	
Cpd	Power dissipation capacitance per inverter	C _L = 50 pF,	f = 1 MHz	32	pF



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NOTES: A. CL includes probe and jig capacitance.

- B. Input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_r = 3 ns, t_f = 3 ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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